

# MuYu

## MY-BT502

Bluetooth 5.2 Low Energy Module

Version 1.1

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## Release Recode

Version	Date	Comments
1.0	2020/06/01	Initial Version
1.1	2022/02/21	Update docs table of contents, update pin descriptions

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# 1. Introduction

## 1.1 Overview

MY-BT502 is a Bluetooth 5.2 Low Energy module. It supports HID, GATT, ATT and other configuration files.

MY-BT502 uses UART as a programming interface, and customers can use AT commands to read or write for the module configuration via UART interface. Can provide more possibilities for customers' applications,

## 1.2 Features

- Bluetooth 5.2 Low Energy
- Stamp hole package
- Low power consumption
- Transmit power: Class 2
- The default UART baud rate is 115200bps, which can support 1200bps to 921.6Kbps
- UART hardware interface
- Support serial port upgrade
- Bluetooth profile support: HID, GATT, ATT, GAP
- Power consumption in working mode (VDD\_3V3 at 3.3V)
- RX mode: 4.5mA @3.3V 0dBm
- TX mode: 4.3mA @3.3V 0dBm
- Deep sleep mode: 2.2uA (RTC wake-up + GPIO wake-up)
- Support Bluetooth SIG Mesh
- Support private Mesh
- Support one-to-many, multi-connection
- Support master mode, master-slave integration



## 1.3 Application

- Consumer electronics
- Health and medical equipment
- Measuring and monitoring system
- Industrial sensors and controls
- Bluetooth car key
- Bluetooth Scanner
- Bluetooth MESH networking
- Lamp lighting

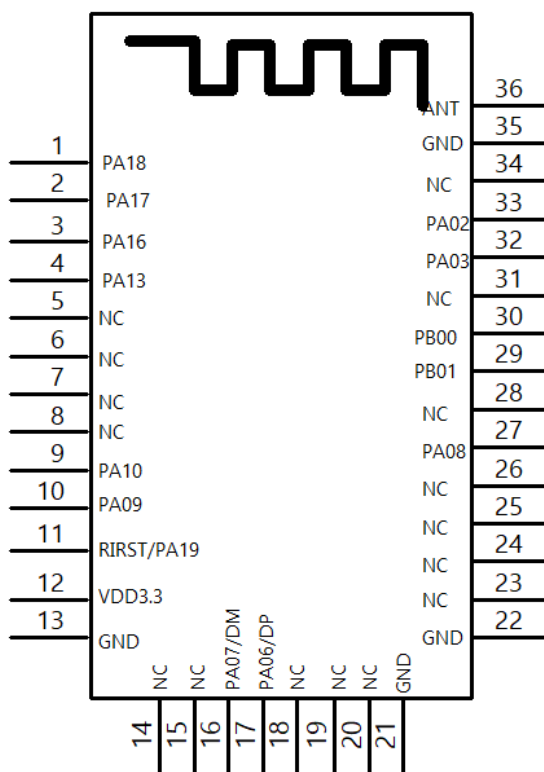
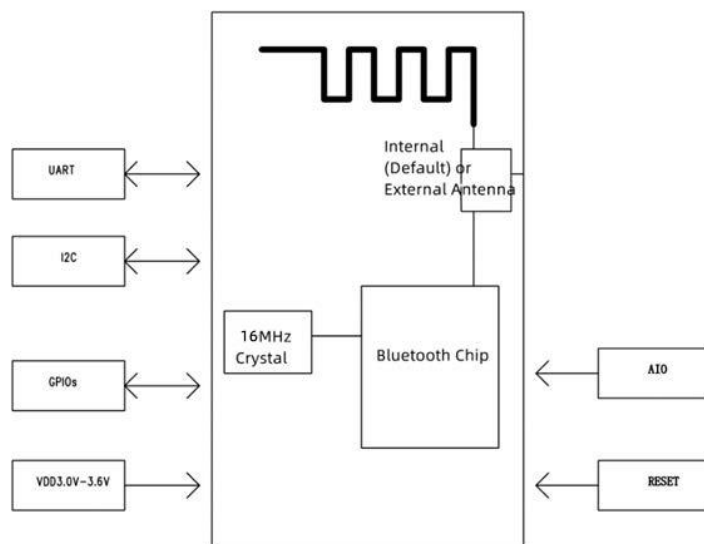
## 2. General Specification

Table1:

Feature	Specification
Model	MY-BT502
Dimensions	13mm(W) X 27mm(L) X 2.2mm(H)
Bluetooth Version	Bluetooth 5.2 Low Energy
Operating Voltage Range	3.0 ~ 3.6V
Transmit Power	6 dBm (Max)
Receive Sensitivity	-97dBm@0.1%BER
Frequency	2.402GHz -2.483GHz ISM band
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK
Crystal	16MHz
Hopping & Channels	1600hops / sec 1MHz channel space 80 Channels
RF Input Impedance	50 $\Omega$
Antenna	PCB Antenna
Interface	UART/I <sup>2</sup> S
Profile	HID, GATT, ATT
Other	Low Energy
Work Temperature	-40°C to +80°C
Storage Temperature	-40°C to +105°C
Humidity	10%~95% Non-Condensing
Environmental	RoHS Compliant

### 3. Hardware Specification

#### 3.1 Block Diagram and PIN Diagram



## 3.2 PIN Definition Descriptions

Table2

Pin	Pin Name	Type	Pin Descriptions
1	PA18_TX	I/O	UART Data Output
2	PA00_RX	I/O	UART Data Input, ADC_CH_4
3	PB16	I/O	UART_CTS Clear to Send, Active Low. Used as normal GPIO by default, ADC_CH_0
4	PB13	I/O	UART_RTS Request to Send, Active Low, Used as normal GPIO by default, ADC_CH_1
5	NC	NC	NC
6	NC	NC	NC
7	NC	NC	NC
8	NC	NC	NC
9	PA10_Tran	I/O	Host MCU change UART Throughput/ Command transmission mode, programmable I/O line (To open this IO function requires the Command of the module, it is not open by default)
10	PA09_Disc	I/O	Host MCU control Bluetooth connection/ disconnect by IO (To open this IO function requires the Command of the module, it is not open by default)
11	PA19_RESET	I	Reset: Active Low
12	VDD_3V3	VDD	Power supply voltage: 3~3.6V
13	GND	VSS	Power Ground
14	NC	NC	NC
15	NC	NC	NC
16	PA07_TX	I/O	Firmware burning port, connected to the RX of the serial tool
17	PA06_RX	I/O	Firmware burning port, connected to the TX of the serial tool
18	NC	NC	NC
19	NC	NC	NC
20	NC	NC	NC
21	GND	VSS	Power Ground
22	GND	VSS	Power Ground
23	NC	NC	NC
24	NC	NC	NC
25	NC	NC	NC
26	NC	NC	NC
27	PA08	I/O	Power mode, low level in running mode, high level in sleep mode
28	NC	NC	NC
29	PB01	I/O	Programmable input/ output line
30	PB00	I/O	Programmable input/ output line
31	NC	NC	NC
32	PA03	I/O	Programmable input/ output line

33	PA02	I/O	BLE connected status pin, disconnected as low, connected as high
34	NC	NC	NC
35	GND	VSS	Antenna power ground
36	EXT_ANT		By default, this PIN is an empty feet. this PIN can connect to an external antenna to improve the Bluetooth signal coverage

## 4. Physical Interface

### 4.1 General Purpose Analog IO

21 general-purpose GPIOs are defined in the module. All these GPIOs can be configured through software to realize various functions, such as button control, LED drive or interrupt signal of the main controller. Hang in the air when not in use, no need to connect to any circuit. The I/O type of each I/O pin can be configured as input or output mode by software.

### 4.2 RF Interface

- 2402–2480 MHz Bluetooth 5.2
- Maximum transmit power: 6 dBm
- Maximum Receive Sensitivity -97dBm@0.1%BER

### 4.3 UART Interface

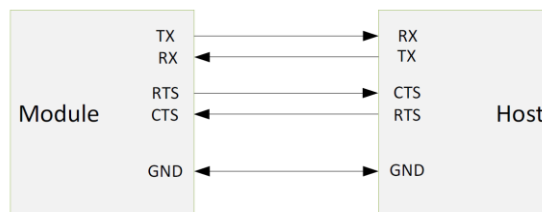
The four signal pins are used to implement the UART function. When MY-BT502 is connected to another digital device, UART\_RX and UART\_TX transfer data between the two devices. The remaining two pins, UART\_CTS and UART\_RTS, can be used to implement RS232 hardware flow control, and they are both active at low level, that is, transmission is allowed at low level and stops at high level.

**Table3:**

Parameter	Value	
Baudrate	Minimum	1200 baud ( $\leq 2\%$ Error)
	Default	115200bps( $\leq 1\%$ Error)
	Max	921600bps( $\leq 1\%$ Error)
Flow control	RTS/CTS, (default none)	
Parity	None, Odd or Even	
Number of stop bits	1	
Bits per channel	8	

When connecting the module to a host, please make sure to follow





## 4.4 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture with a resolution up to 12bits at up to 1MSPS.

Transfer Range: VSS to VDDA (3.0~3.6V)

In addition to the IO AD channel, there are three internal channels: the chip operating temperature channel ADC\_CH\_9, the chip operating voltage VBAT channel ADC\_CH10, and the chip internal ADC reference voltage (standard 1.4V) channel ADC\_CH11.

## 5.5. Electrical Characteristics

### 5.1 Absolute Maximum Ratings

The absolute maximum ratings of the supply voltage and voltage on the digital and analog pins of the module are listed below. Exceeding these values will cause permanent damage. The average GPIO pin output current is defined as the average current value flowing through any corresponding pin in a 100ms period. The total average GPIO pin output current is defined as the average current value flowing through all corresponding pins in a 100ms period. The maximum output current is defined as the peak current value flowing through any corresponding pin.

**Table4:** Maximum Ratings

Parameter	Min	Max	Unit
V <sub>IN</sub> - I/O (VDDIO)	-0.3	+3.6	V
V <sub>IN</sub> - (VDD)	-0.3	+3.6	V
T <sub>OT</sub> – Operating Temperature	-40	+80	°C
T <sub>ST</sub> - Storage Temperature	-40	+105	°C

### 5.2 Recommended Operating Conditions

**Table5:**

Parameter	Min	Typ	Max	Unit
V <sub>IN</sub> -Terminal voltages (VDD)	3.0	3.3	3.6	V
V <sub>IN</sub> -I/O Voltages (VDDIO)	3.0	3.3	3.6	V

## 6.ESD & MSL

Table6:

Parameter	Value
MSL:	Grade: 3
ESD:	HBM: Class-2
	CDM: Class-B

## 7.Recommended Temperature Reflow Profile

Prior to any reflow, it is important to ensure the modules were packaged to prevent moisture absorption. New packages contain desiccate (to absorb moisture) and a humidity indicator card to display the level maintained during storage and shipment. If directed to bake units on the card, please check the Picture below and follow instructions specified by IPC/JEDEC J-STD-033.

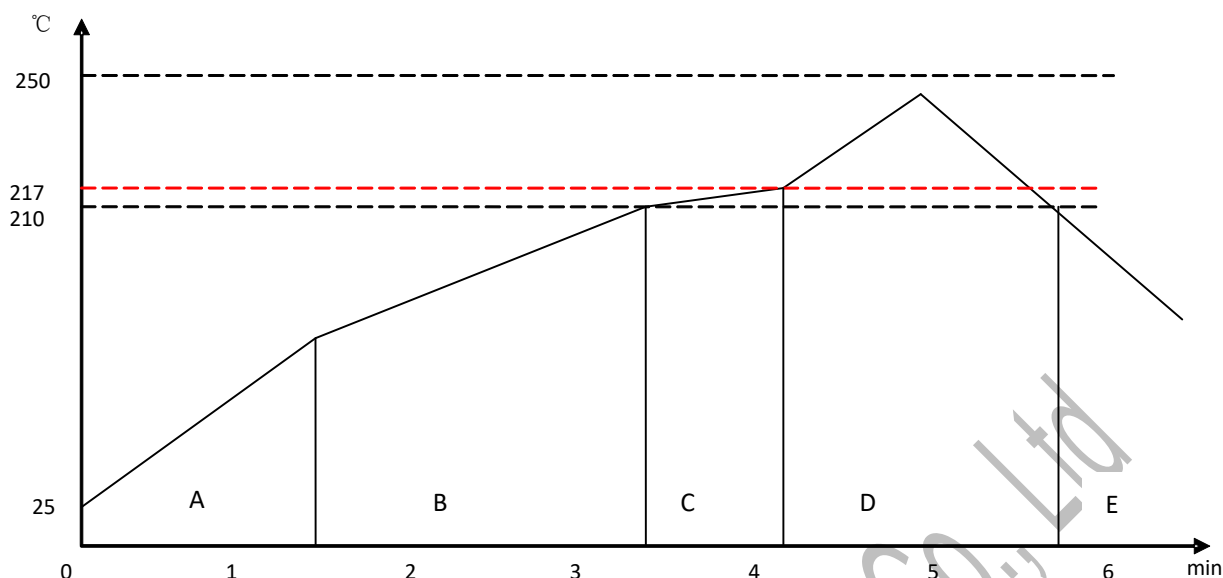
**Note:** The shipping tray cannot be heated above 65°C. If baking is required at the higher temperatures displayed in the Picture below, the modules must be removed from the shipping tray.

Any modules not manufactured before exceeding their floor life should be re-packaged with fresh desiccate and a new humidity indicator card. Floor life for MSL (Moisture Sensitivity Level) 3 devices is 168 hours in ambient environment 30°C/60%RH.

Table 7: Recommended baking times and temperatures

MSL	125°C Baking Temp		90°C/≤ 5%RH Baking Temp		40°C/ ≤ 5%RH Baking Temp	
	Saturated @ 30°C/85%	Floor Life Limit + 72 hours@ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72 hours@ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72hours@ 30°C/60%
3	9 hours	7 hours	33hours	23 hours	13 days	9 days

The design of the surface mount module is easy to manufacture, including reflow soldering to the PCB motherboard. Ultimately, it is the customer's responsibility to choose a suitable solder paste and ensure that the furnace temperature during reflow meets the requirements of the solder paste. The surface mount module complies with the J-STD-020D1 standard for reflow soldering temperature. The welding profile depends on the various parameters that need to be set for each application. The data here is only for the guidance of reflow soldering



Typical Lead-free-flow

**Preheating zone (A)**-This zone heats up at a controlled rate, with a typical value of 0.5-2°C/s. The purpose of this area is to preheat the PCB board and components to 120~150°C. At this stage, the heat needs to be evenly distributed to the PCB board, and the solvent is completely removed to reduce the thermal shock of the components.

**Equilibrium Zone 1 (B)**-At this stage, the flux becomes soft and evenly encapsulates the solder particles and spreads them on the PCB board to prevent them from being re-oxidized. As the temperature rises and the flux is liquefied, each activator and rosin are activated and begin to eliminate the oxide film formed on the surface of each solder particle and PCB board. For this area, the recommended temperature is 150° to 210°, and the time is 60 to 120 seconds.

**Equilibrium zone 2 (C) (optional)**-In order to solve the problem of upright parts, it is recommended to keep the temperature at 210-217°C for about 20 to 30 seconds.

**Reflow zone (D)**-The curve in the figure is designed for Sn / Ag3.0 / Cu0.5. It can be a reference for other lead-free solders. The peak temperature should be high enough to achieve good wettability, but not too high to cause discoloration or damage to the component. Excessive welding time will lead to intermetallic growth, leading to brittle solder joints. The recommended peak temperature (Tp) is 230~250°C. When the temperature is higher than 217°C, the welding time should be 30 to 90 seconds.

**Cooling zone (E)**-The cooling rate should be fast to keep the solder particles small, which will provide a longer lasting solder joint. The typical cooling rate should be 4°C.

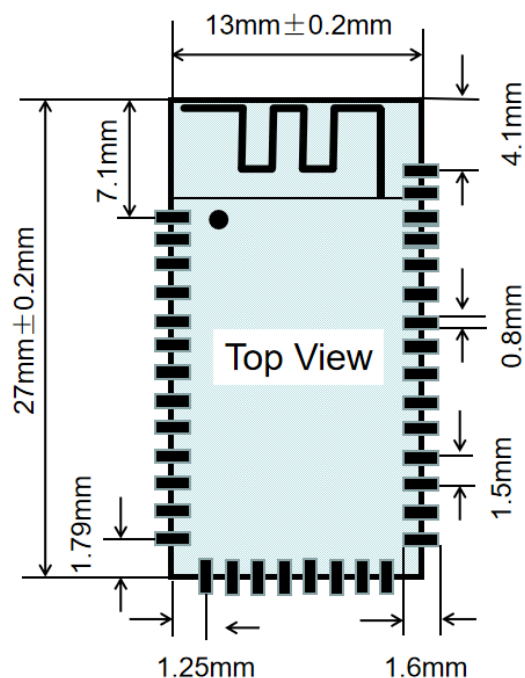
## 8. Mechanical Detail

### 8.1 Physical Dimensions

- Dimension: 13mm(W) x 27mm(L) x 2.2 mm(H) Tolerance: ±0.2mm

## MY-BT502 Datasheet

- Pad size: 1.6mmX0.8mm Tolerance:  $\pm 0.1\text{mm}$
- Pad pitch: 1.5mm Tolerance:  $\pm 0.1\text{mm}$



## 9. Hardware Integration Suggestions

### 9.1 Soldering Recommendations

MY-BT502 is compatible with the industry standard reflow profile of lead-free solder. The reflow profile used depends on the thermal quality of the entire assembled PCB, the heat transfer efficiency of the oven, and the specific type of solder paste used. Please refer to the data sheet of the specific solder paste for the profile configuration.

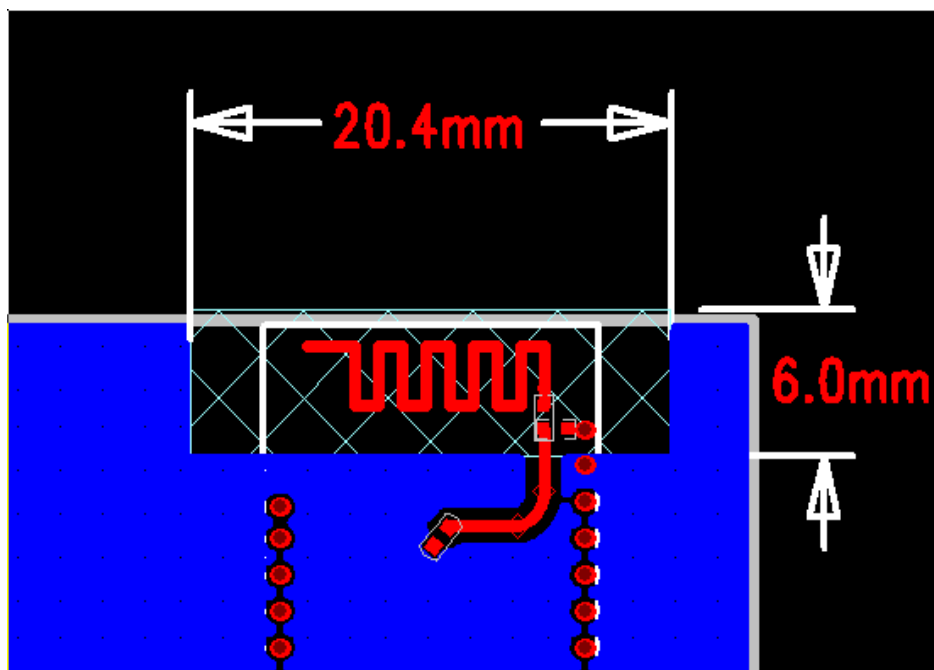
Muyu will provide the following suggestions for welding modules to ensure the reliability of the solder joints and operations of the modules after welding. Since the reflow profile used is dependent on the process and layout, the best reflow profile should be studied on a case-by-case basis. Therefore, the following recommendations should be used as a starting point.

### 9.2 Layout Guidelines (Internal Antenna)

It is strongly recommended to use good layout practices to ensure the normal operation of the module. Placing copper or any metal close to the antenna will affect the performance of the antenna, thereby deteriorating the working efficiency of the antenna. The metal shield around the antenna will prevent signal radiation, so the metal casing should not be used with the module. Please use more grounding vias at the edge of the grounding area.

The following suggestions can help avoid EMC problems in the design. Please note that each design is unique, and the following description does not consider all basic design rules, such as avoiding capacitive coupling between signal lines. The following description aims to avoid EMC problems caused by the RF part of the module. Please consider carefully to avoid problems with the digital signal in the design.

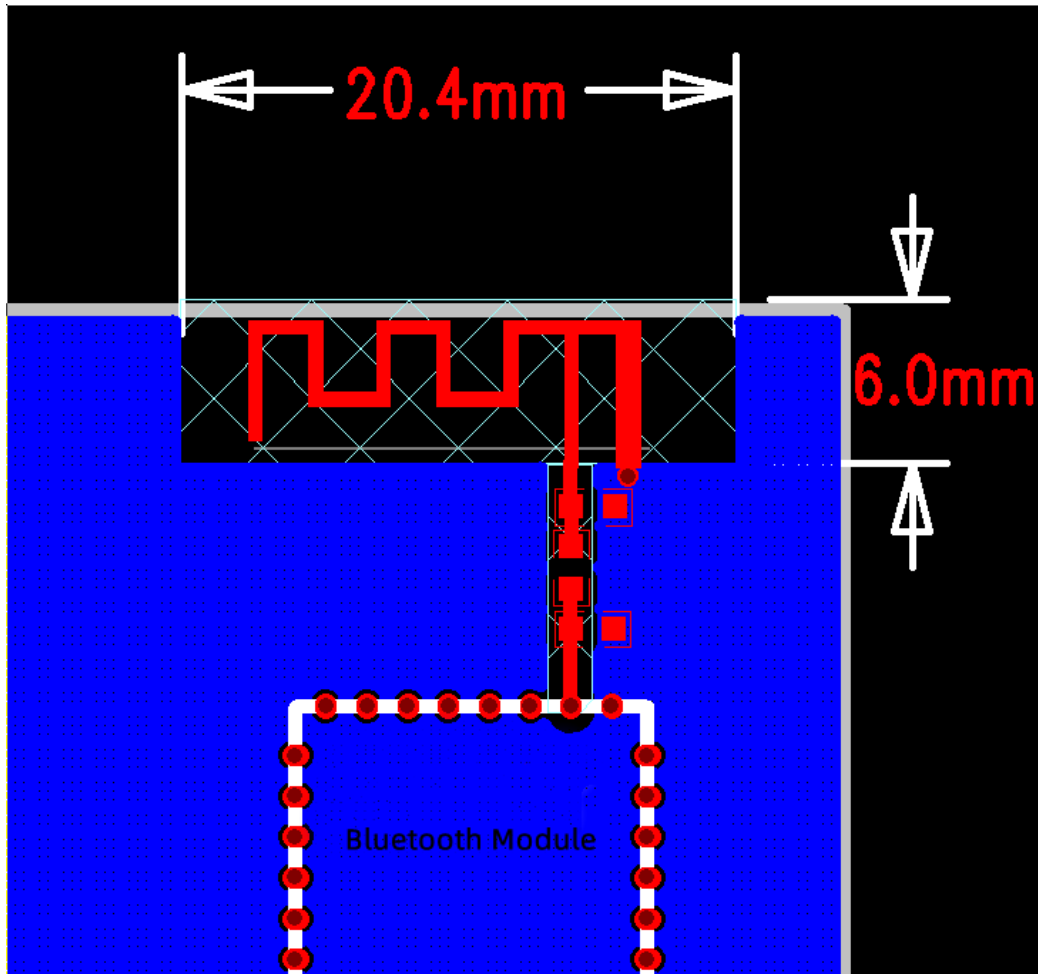
Make sure that the loop of the signal wire is as short as possible. For example, if the signal enters the inner layer through vias, always use ground vias around the pad. And place them closely and symmetrically around the signal vias. Any sensitive signal traces and loops should be completed on the inner layer of the PCB as much as possible. Sensitive signal lines should have an area surrounded by ground wires above and below. If this is not possible, make sure that the return path is shortest (for example, use the ground wire next to the signal wire)



### 9.3 Layout Guidelines (External Antenna)

In the absence of on-board antenna design, module placement and PCB layout are critical to optimizing module RF performance.

1. The microstrip line (the wiring from the antenna to the EXT\_ANT port on the module end) should be 50Ω;
2. The microstrip line should be as straight as possible and as short as possible. When it is necessary to turn, it should be as arc as possible;
3. The width of the microstrip line is about 0.5mm, and the distance between the copper coating and the microstrip line is about 0.5mm;
4. To avoid interference to the module signal; the location of the external antenna and the EXT\_ANT port of the module should be far away from any noise sources and digital lines, the antenna should be placed close to the board, no components and copper should be placed around, and no wiring should be placed as far as possible, Keep it intact;
5. A  $\Pi$ -type matching network circuit is needed between the microstrip lines, and placed as close to the antenna as possible to better match the impedance;
6. The RF key circuit of the module should be clearly separated from any digital circuit on the system board



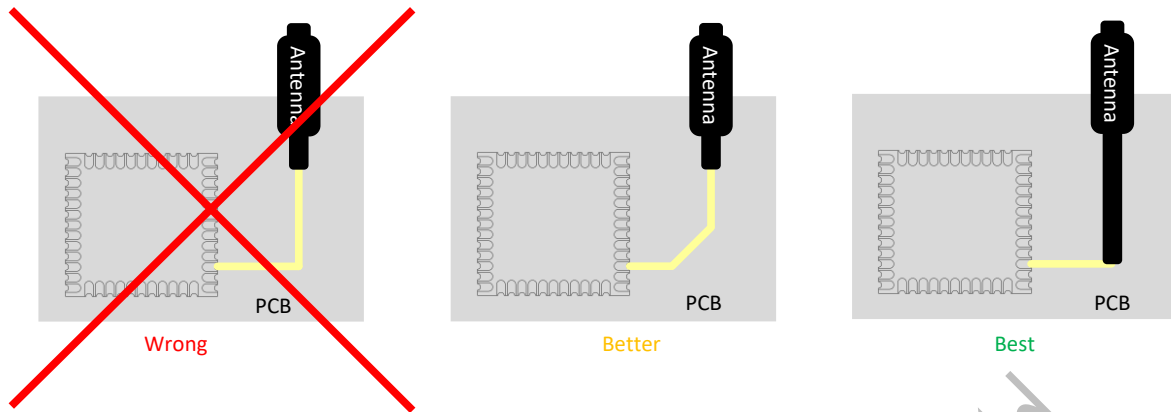
#### 9.4 General Design Suggestions:

Wireless products are not suitable for the use of external metal casings and large metal components around them. The length of PCB traces or wires should be as short as possible.

The distance between the connection on the top layer and the ground area should be at least as large as the thickness of the dielectric.

Avoid placing RF close to the digital part of the system board.

In order to reduce signal loss, avoid wiring the microstrip line in sharp corners. Chamfered or rounded wiring is preferred to rectangular wiring; 45-degree oblique wiring is better than pure 90-degree wiring.



1 **Figure 11:** Recommended Trace Connects Antenna and the Module

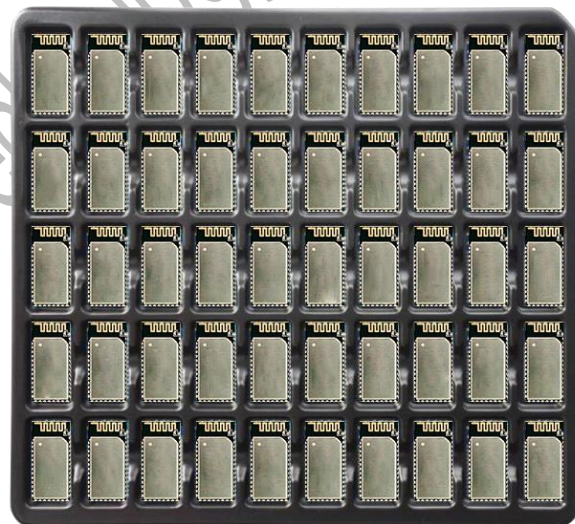
## 10. Product Packaging Information

Pallet packaging

Pallet size: 180mm \* 195mm

50pcs/Pallet

MOQ: 1000pcs



# 11. Application Schematic

